

Material Declaration Report

Package Type:	UQFN 10L
Pericom Package Code:	ZM10(Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	3.5410
Termination Plating:	NiPdAu
JESD 97 Pb-free Category:	e4
Plating Thickness (um):	0.5~2.2
Tin Whisker Mitigation:	N/A

MSL Rating:	1
Peak Body Temp (C):	260
Max Time (sec):	30
Reflow Cycles:	3
Rev Date:	10/28/2009

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	2.4900	UTL	Silica fuse	60676-86-0	90.500	2.2535
			Epoxy resin	Proprietary	4.500	0.1121
			Phenol resin	Proprietary	4.500	0.1121
			Carbon black	1333-86-4	0.500	0.0125
LEADFRAME	0.6060		Copper (Cu)	7440-50-8	97.933	0.5935
			Chrome	24613-89-6	0.246	0.0015
			Tin	7440-31-5	0.247	0.0015
			Zinc	7440-66-6	0.217	0.0013
			Nickel	7440-02-0	1.280	0.0078
			Palladium	7440-05-3	0.049	0.0003
			Gold	7440-57-5	0.030	0.0002
SILICON DIE	0.2360		Silicon (Si)	7440-21-3	99.192	0.2341
			Non-hazardous Metal	Proprietary	0.808	0.0019
DIE ATTACH EPOXY	0.1010		Epoxy Resin	Proprietary	31.000	0.0313
			Metal Oxide	Proprietary	31.000	0.0313
			Glycol Ethers	Proprietary	21.000	0.0212
			Curing Agent & Hardener	Proprietary	8.500	0.0086
			Treated Silica	14808-60-7	8.500	0.0086
GOLD WIRE	0.1080		Gold(Au)	7440-57-5	99.990	0.1080
			Impurities	-	0.010	0.0000

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

	MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Device	Mold Compound	<2	<2	<2	<2	<5	<5
	Leadframe	<50	<2	<2	<2	<5	<5
	Silicon Die	<2	<2	<2	<2	<5	<5
	Die Attach Epoxy	<2	<2	<2	<2	<5	<5
	Gold Wire	<2	<2	<2	<2	<5	<5
	Solder Plating	<2	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC and China RoHS Directive SJ/T11363-2006	<p>Declaration Statement: Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium</p>																	
	<table border="1"> <thead> <tr> <th>Pb</th> <th>Hg</th> <th>Cr+6</th> <th>Cd</th> <th>PBB</th> <th>PBDE</th> </tr> </thead> <tbody> <tr> <td><1000ppm</td> <td><1000ppm</td> <td><1000ppm</td> <td><100ppm</td> <td><1000ppm</td> <td><1000ppm</td> </tr> <tr> <td>O</td> <td>O</td> <td>O</td> <td>O</td> <td>O</td> <td>O</td> </tr> </tbody> </table> <p>O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006. X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.</p>	Pb	Hg	Cr+6	Cd	PBB	PBDE	<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm	O	O	O	O	O
Pb	Hg	Cr+6	Cd	PBB	PBDE													
<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm													
O	O	O	O	O	O													